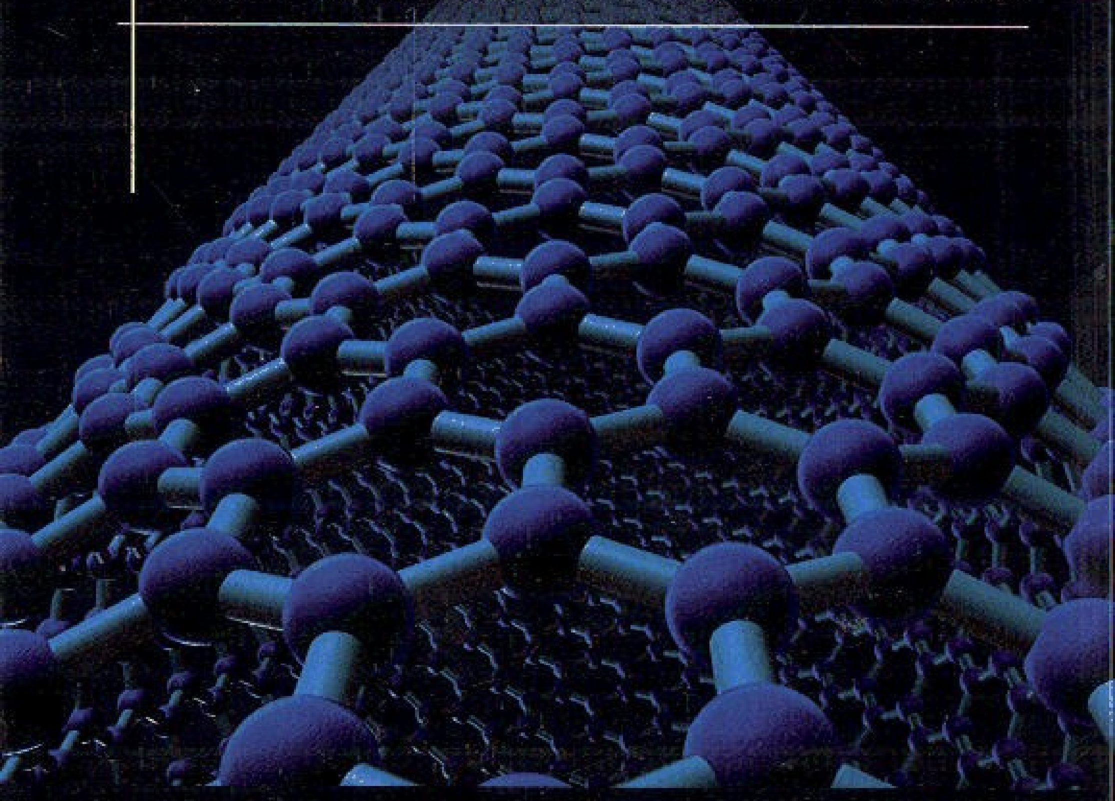
McGraw-Hill Nanoscience and Technology Series

MEMS/MOEMS PACKAGING

CONCEPTS, DESIGNS, MATERIALS, AND PROCESSES



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